



Final Product/Process Change Notification
Document #:FPCN25523X
Issue Date:07 Nov 2024

Title of Change:	SOIC16 PCC Wire Conversion and leadframe change										
Proposed First Ship date:	14 Feb 2025 or earlier if approved by customer										
Contact Information:	Contact your local onsemi Sales Office or Dianne.Calva@onsemi.com										
PCN Samples Contact:	<p>Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.</p>										
Additional Reliability Data:	Contact your local onsemi Sales Office or Nhel.Malonzo@onsemi.com										
Type of Notification:	<p>This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com</p>										
Marking of Parts/ Traceability of Change:	Can be identified by lot code										
Change Category:	Assembly Change										
Change Sub-Category(s):	Material Change										
Sites Affected:											
onsemi Sites	External Foundry/Subcon Sites										
onsemi Carmona, Philippines	None										
Description and Purpose:											
Change lead frame from Std RPPF (Flag Size: 70x70mil) to EHDLF RPPF (Flag Size: 90x130mil) and Au to PCC Wire Conversion.											
<table border="1"><thead><tr><th></th><th>From</th><th>To</th></tr></thead><tbody><tr><td>LeadFrame</td><td>Std RPPF Etched (Flag Size: 70x70mil)</td><td>EHDLF RPPF Stamped (Flag Size: 90x130mil)</td></tr><tr><td>Bond Wire</td><td>Au Wire 0.8mil</td><td>PCC Wire 0.8mil</td></tr></tbody></table>				From	To	LeadFrame	Std RPPF Etched (Flag Size: 70x70mil)	EHDLF RPPF Stamped (Flag Size: 90x130mil)	Bond Wire	Au Wire 0.8mil	PCC Wire 0.8mil
	From	To									
LeadFrame	Std RPPF Etched (Flag Size: 70x70mil)	EHDLF RPPF Stamped (Flag Size: 90x130mil)									
Bond Wire	Au Wire 0.8mil	PCC Wire 0.8mil									
There is no product marking change as a result of this change.											



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Reliability Data Summary:

QV DEVICE NAME: NCV5700DR2G

RMS: 091678

PACKAGE: SOIC 16

Test	Specification	Condition	Interval	Results
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260°C		0/693
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0/231
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
Solderability	JSTD002	Ta = 245°C, 5 sec		0/45
Physical Dimensions	JESD22-B120			0/30

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
NCD5702DR2G	NCV5700DR2G
NCD5700DR2G	NCV5700DR2G